

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1178sw#trpbf

(Engineering Calculation)

SOIC WIDE

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**TOTAL MASS (g) : 0.248481**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004001	1000000	16101.8115234		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000167	1000000	672.082580566		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.138021	975000	555458.1875		
		Iron (Fe)	7439-89-6	0.003397	24000	13671.0449219		
		Phosphorus (P)	7723-14-0	0.000042	300	169.026748657		
		Zinc (Zn)	7440-66-6	0.000099	700	398.420196533		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.141559</b>	<b>1000000</b>	<b>569696.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.004771	1000000	19202.1171875		
		<b>External Plating Total:</b>				<b>0.004771</b>	<b>1000000</b>	<b>19202.1171875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001132	1000000	4555.67382812		
<b>Internal Plating Total:</b>				<b>0.001132</b>	<b>1000000</b>	<b>4555.67382812</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001102	750000	4434.94042969		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000367	250000	1476.97192383		
<b>Die Attach Total:</b>				<b>0.001469</b>	<b>1000000</b>	<b>5911.91210938</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.009783	103000	39371.1640625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.085006	895000	342102.125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000190	2000	764.644897461		
		<b>Encapsulation Total:</b>				<b>0.094979</b>	<b>1000000</b>	<b>382237.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000403	1000000	1621.85205078		
					<b>TOTAL MASS (g) :</b>	<b>0.248481</b>		